



Taiwan 3DS-IC Committee Meeting Summary and Minutes

Taiwan 3DS-IC TC Meeting April 30. 2013,14:00-16:00 SEMI Taiwan, HsinChu

Next Committee Meeting

July 30, 2013

3DS-IC TC Meeting, ITRI, HsinChu

Committee Announcements (optional)

Table 1 Meeting Attendees:

Co-Chairs: Dr. TK Ku (ITRI) **SEMI Staff:** Catherine Chang

Company	Last	First	Company	Last	First
KYEC	Chen	Wendy	SEMATECH	Yang	Terry
ITRI	Ku	TK	ITRI	YLiHeng	Lee
ITRI-CMS	Yao	Bin-Cheng	NTUST		Chao- Chang
CMPUG TW	Kong	LC	KYEC	Sam	Kao
ITRI	Chen	Erh-Hao			

Table 2 Leadership Changes

Group	Previous Leader	New Leader
Testing Task Force		Dr. Li-Heng Lee (ITRI, lihenglee@itri.org.tw)

Table 3 Ballot Results

Passed ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

Failed ballots and line items were returned to the originating task forces for re-work and re-balloting.

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Document #	Document Title	Committee Action
5474	New Standard: Guide for CMP and Micro-Bump Processes for Frontside TSV	Passed as with editorial changes

Table 4 Authorized Activities

#	Туре	SC/TF/WG	Details
None			

Note: SNARFs and TFOFs are available for review on the SEMI Web site at: http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 5 Authorized Ballots

#	When	SC/TF/WG	Details
5473	Cycle 4,	Middle-End	New Standard: Guide for Alignment Mark for 3DS-IC Process
	2013	Process TF	





Table 6 New Action Items

Item #	Assigned to	Details
None		

Table 7 Previous Meeting Actions Items

Task Force leader changed for Testing Task Force.

1 Welcome, Reminders, and Introductions

Dr. TK Ku called the meeting to order at 14:00. The meeting reminders on antitrust issues, intellectual property issues and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01, SEMI Standards Required Meeting Elements

2 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting.

3 Staff Report

North America Standards Spring 2013 Meetings

4 Liaison Reports

- 4.1 Dr. TK Ku presented the NA Liaison Report:
 - Upcoming NA 3DS-IC Ballots

* Voting Period – Cycle 1, 2013 *				
Doc #	Document Title	Task Force		
5173C	New Standard: Guide for Describing Materials Properties for a 300 mm 3DS-IC Wafer Stack	Bonded Wafer Stacks TF		
5410	New Standard: Guide for Metrology Techniques to be Used in Measurement of Geometrical Parameters of Through-Silicon Vias (TSVs) in 3DS-IC Structures	Inspection & Metrology TF		
5175	New Standard: Guide for Multi-Wafer Transport and Storage Containers for 300 mm, Thin Silicon Wafers on Tape Frames	Thin Wafer Handling		

Attachment: 02, NA 3DS-IC Liaison Report

5 Ballot Review

Passed ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review. **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting.

NOTE 1:Committee adjudication on Cycle 2 ballots are detailed in the Audits & Reviews (A&R) Subcommittee Forms for procedural review. These A&R forms are available as attachments to these minutes. The attachment number for each document is provided below the summary tables.

5.1 Cycle2 Ballots

Document #	Document Title	Committee Action
5474	rice Standard. Guide for Civil and where-Bump riceesses for richtside 15 v	Passed as with editorial changes

Attachment: 03, Ballot Review for Doc. 5474





6 Old Business

None.

7 New Business

None.

8 Action Item Review

8.1 Open Action Items

None.

8.2 New Action Items

None.

9 Next Meeting and Adjournment

July 30, 2013 3DS-IC TC Meeting, ITRI, HsinChu

Respectfully submitted by:

Catherine Chang Sr. Manager SEMI Taiwan

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Minutes approved by:

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TK Ku/ITRI, Co-Chair	June 13, 2013

Table 8 Index of Available Attachments #1

#	Title		Title
1	1 Required Elements 2011		
2	NA 3DS-IC Liaison Report		
3	Ballot Review for Doc. 5474		

^{#1} Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact [SEMI Staff Name] at the contact information above.